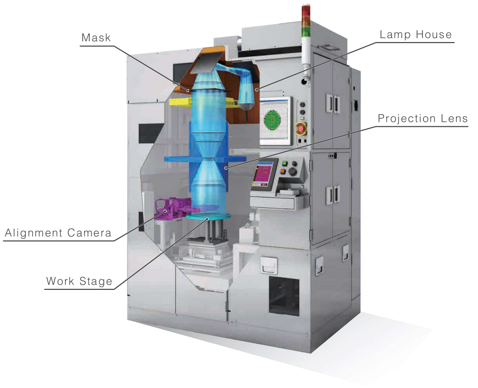
UX-4 Full-Field Projection Aligner

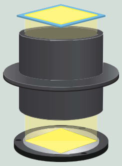
Resolution	2µm L/S〜
Overlay	Top Side : ±1µm, Back Side : ±1.5µm
Throughput	120wph
Wafer Size	Φ100mm / 150mm / 200mm Si, Sapphire, GaN, GaAs, SiC, Glass
Wafer Transfer	Cassette to Cassette Automatic

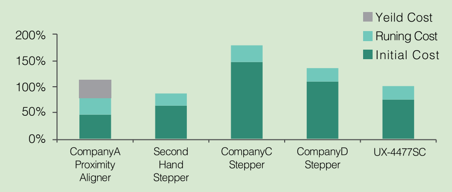


Benefit for customers

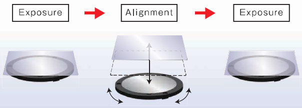
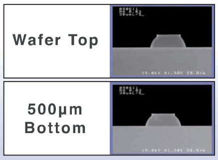
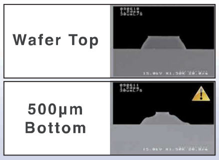
✓Flexible on surface shape

✓Higher productivity with no-mask damage system/ One shot per wafers





Advantage of Full-Field Projection Lithography

	UX-4(Full-Field Projection)	Proximity/Contact Aligner
Mask Damage Free	 Good No mask-wafer contact throughout the process.	Not Good 
High Productivity	 Good Full-Field Projection > Proximity/Contact Aligner	Not Good 
3D Lithography	 Good Large Depth of Focus. High resolution on both top and bottom of step.	Not Good 
Thick Resist Process	 Good No mask-wafer sticking problem with thick-sticky resist.	Not Good